DATA SHEET

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MOS FIELD EFFECT TRANSISTOR
2SK3297

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

The 2SK3297 is N-channel DMOS FET device that features a low gate charge and excellent switching characteristics, and designed for high voltage applications such as switching power supply, AC adapter.

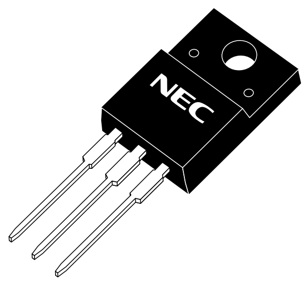
ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3297	Isolated TO-220

FEATURES

- Low gate charge
  Q_G = 18 nC TYP. (V_{DD} = 450 V, V_{GS} = 10 V, I_D = 5.0 A)
- Gate voltage rating ±30 V
- Low on-state resistance
  $R_{DS(ON)}$ = 1.6 Ω MAX. (V_{GS} = 10 V, I_D = 2.5 V)
- Avalanche capability ratings
- Isolated TO-220 package

(Isolated TO-220)



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	600	V
Gate to Source Voltage (V_{DS} = 0 V)	V_{GSS}	±30	V
Drain Current(DC) (T_C = 25°C)	$I_{D(DC)}$	±5.0	A
Drain Current(pulse) Note1	$I_{D(pulse)}$	±20	A
Total Power Dissipation (T_A = 25°C)	P_{T1}	2.0	W
Total Power Dissipation (T_C = 25°C)	P_{T2}	35	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C
Single Avalanche Current Note2	I_{AS}	5.0	A
Single Avalanche Energy Note2	E_{AS}	16.7	mJ

Notes1. PW ≤ 10 μs, Duty Cycle ≤ 1%

2. Starting T_{ch} = 25°C, V_{DD} = 150 V, R_G = 25 Ω , V_{GS} = 20 → 0 V

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

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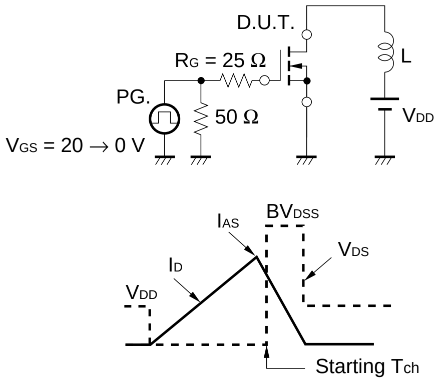
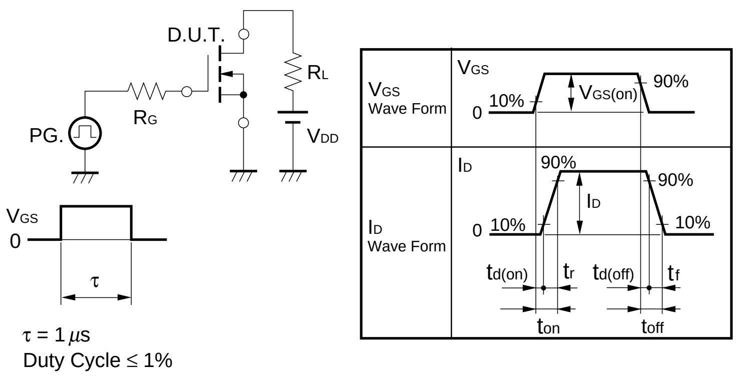
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 600 V, V_{GS} = 0 V			100	μA
Gate Leakage Current	I_{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V			±100	nA
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	2.5		3.5	V
Forward Transfer Admittance	$\| y_{fs} \|$	V_{DS} = 10 V, I_D = 2.5 A	1.5			S
Drain to Source On-state Resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 2.5 A		1.3	1.6	Ω
Input Capacitance	C_{iss}	V_{DS} = 10 V		750		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		130		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		9.7		pF
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 150 V, I_D = 2.5 A		17		ns
Rise Time	t_r	$V_{GS(on)}$ = 10 V		3		ns
Turn-off Delay Time	$t_{d(off)}$	R_G = 10 Ω		37		ns
Fall Time	t_f			10		ns
Total Gate Charge	Q_G	V_{DD} = 450 V		18		nC
Gate to Source Charge	Q_{GS}	V_{GS} = 10 V		4		nC
Gate to Drain Charge	Q_{GD}	I_D = 5.0 A		7		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 5.0 A, V_{GS} = 0 V		0.9		V
Reverse Recovery Time	t_{rr}	I_F = 5.0 A, V_{GS} = 0 V		1.4		μs
Reverse Recovery Charge	Q_{rr}	di/dt = 50 A/μs		5.3		μC

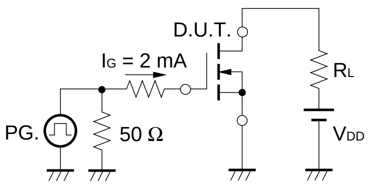
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME



TEST CIRCUIT 3 GATE CHARGE



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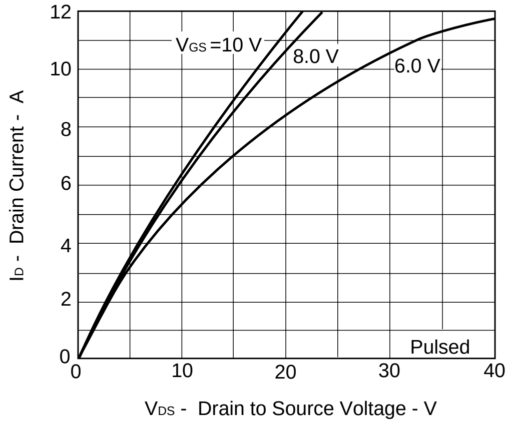
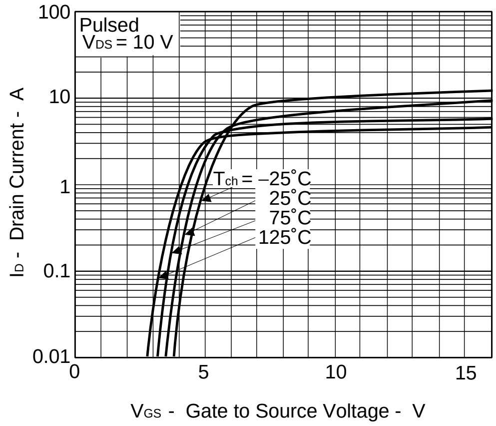
TYPICAL CHARACTERISTICS

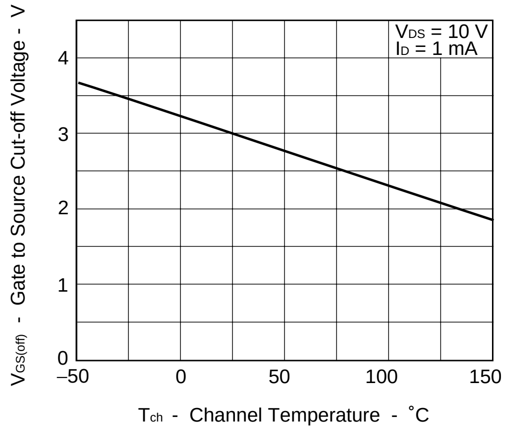
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



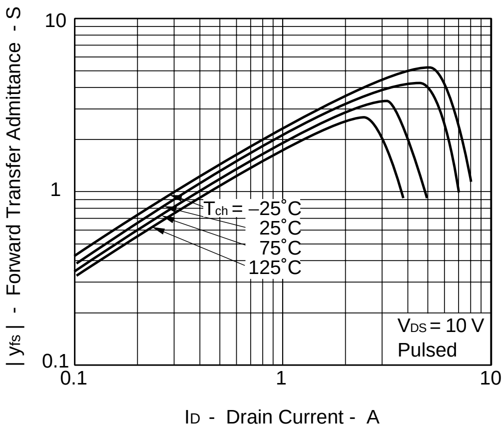
FORWARD TRANSFER CHARACTERISTICS



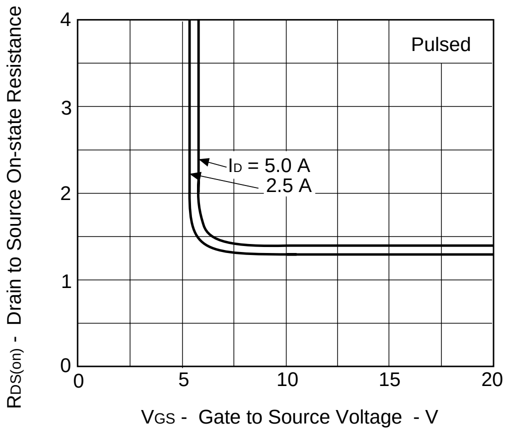
GATE TO SOURCE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



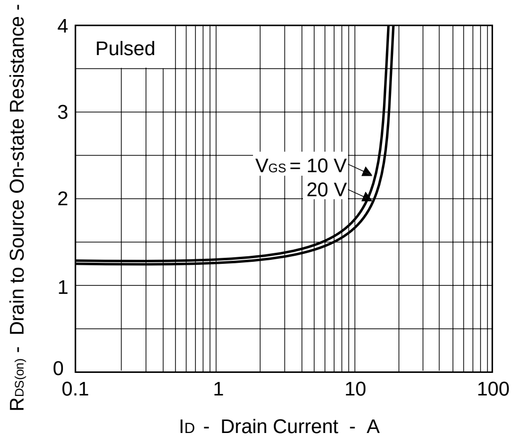
FORWARD TRANSFER ADMITTANCE vs.
DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



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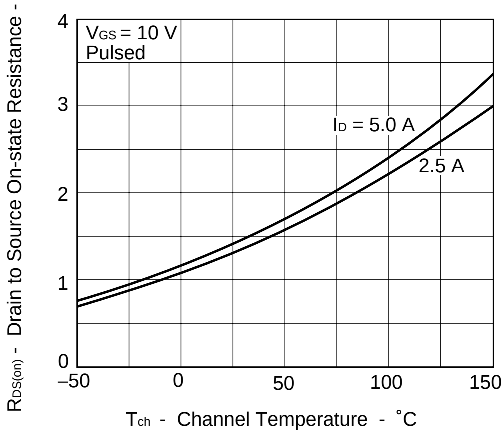
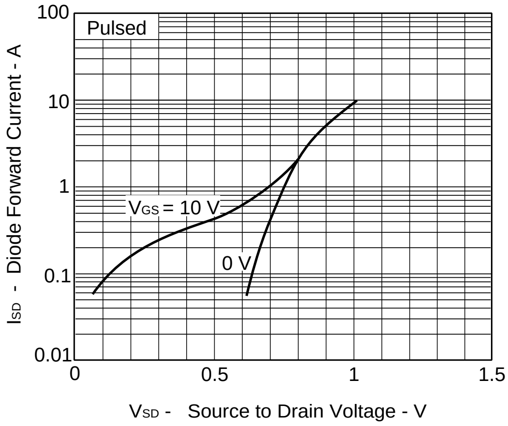
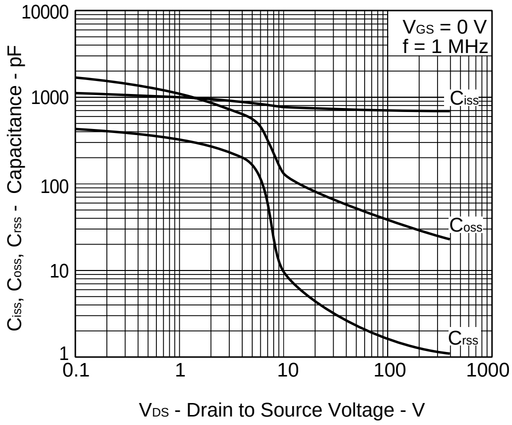
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
CHANNEL TEMPERATURE



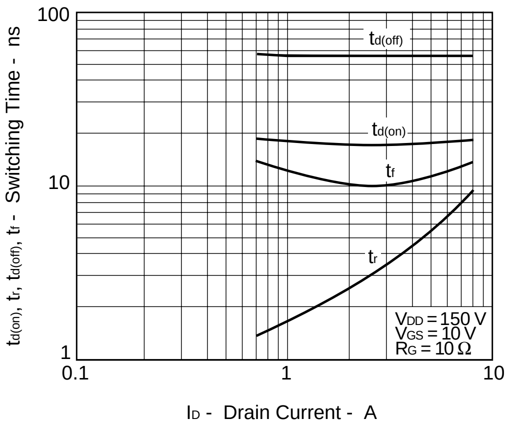
SOURCE TO DRAIN DIODE
FORWARD VOLTAGE



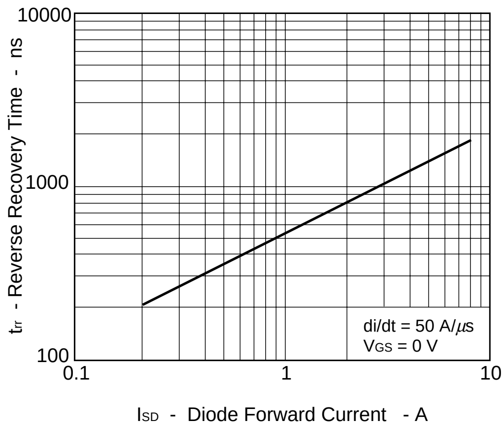
CAPACITANCE vs. DRAIN TO
SOURCE VOLTAGE



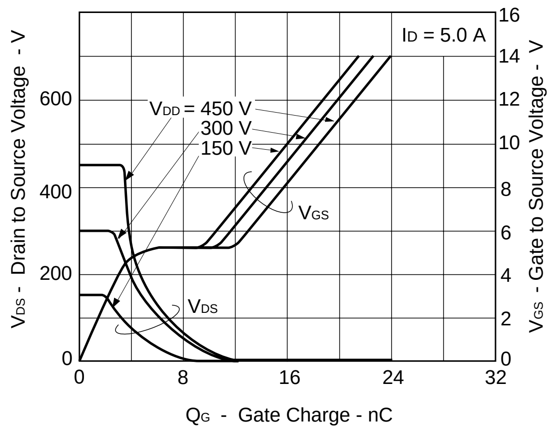
SWITCHING CHARACTERISTICS



REVERSE RECOVERY TIME vs.
DIODE FORWARD CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



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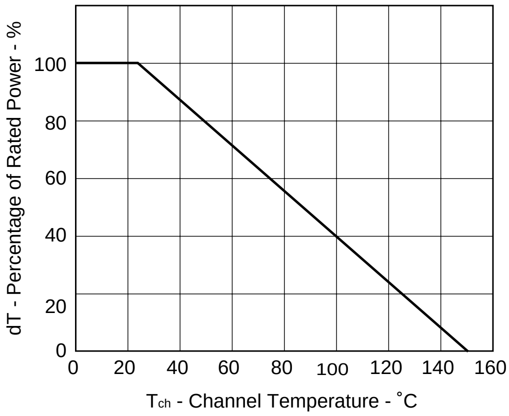
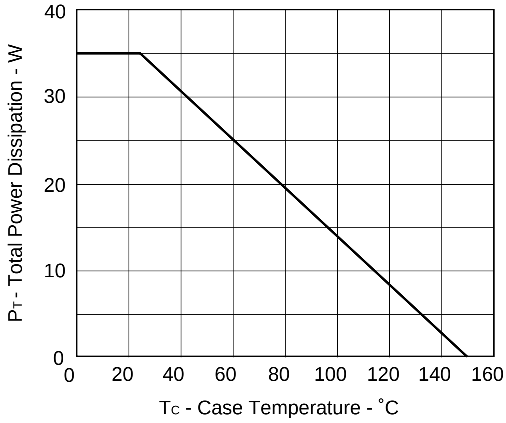
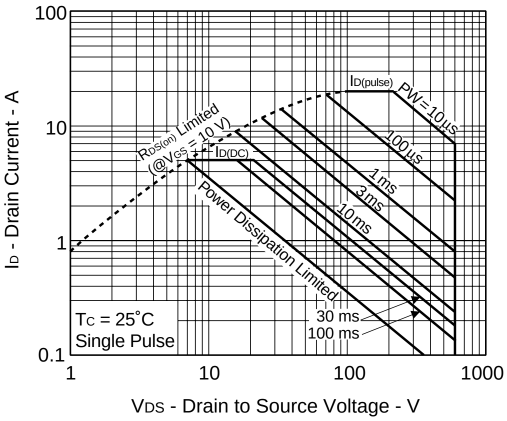
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



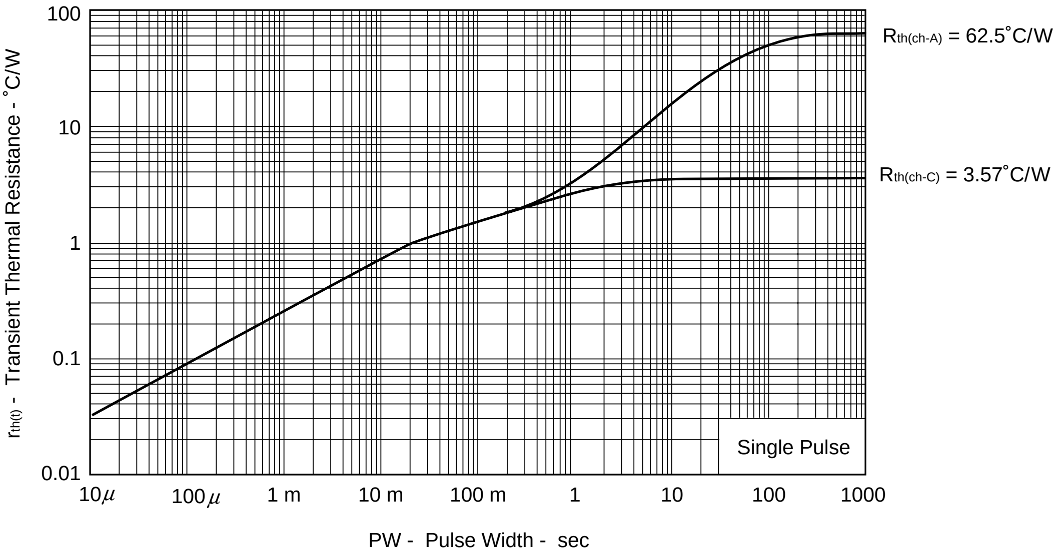
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA



TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



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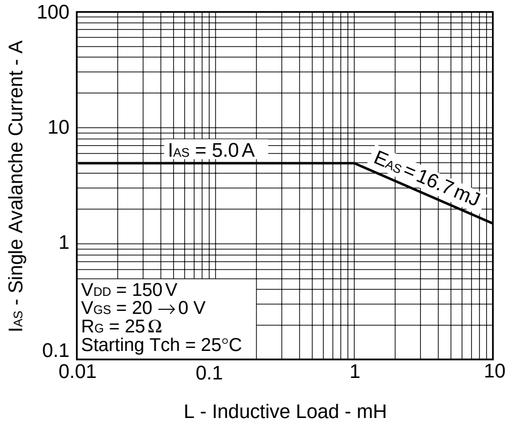
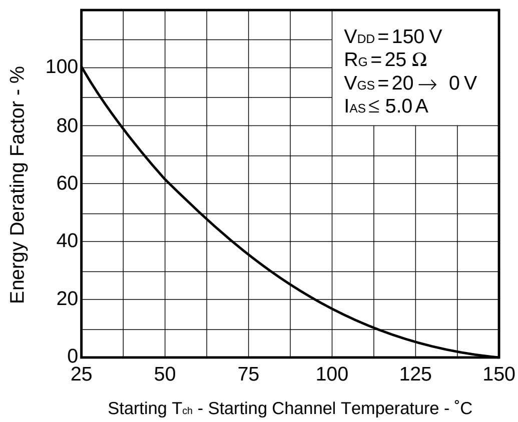
SINGLE AVALANCHE CURRENT vs.
INDUCTIVE LOAD



SINGLE AVALANCHE ENERGY
DERATING FACTOR



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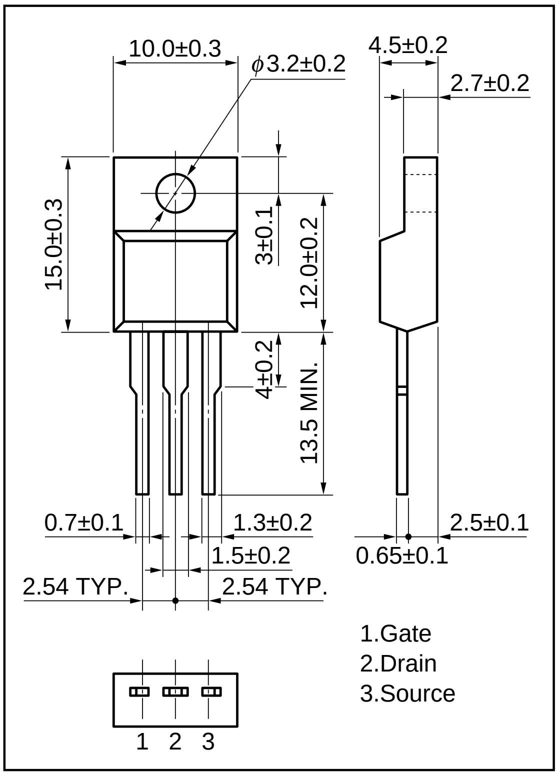
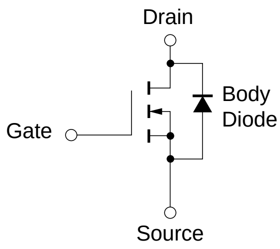
PACKAGE DRAWING(Unit: mm)

Isolated TO-220 (MP-45F)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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